

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	3555	(substrate wafer semiconductor mask) and ceramic and fiber and (dry\$3 dri\$3) and binder and impregnat\$4	US-PGPUB ; USPAT ; USOCR ; EPO; JPO; DERWE NT	2006/05/2 2 11:49
2	BRS	L2	532	(substrate wafer semiconductor mask) and ceramic and fiber and (dry\$3 dri\$3) and binder and impregnat\$4 and calcin\$4 and fir\$3	US-PGPUB ; USPAT ; USOCR ; EPO; JPO; DERWE NT	2006/05/2 2 11:49
3	BRS	L3	499	(substrate) and ceramic and fiber and (dry\$3 dri\$3) and binder and impregnat\$4 and calcin\$4 and fir\$3	US-PGPUB ; USPAT ; USOCR ; EPO; JPO; DERWE NT	2006/05/2 2 11:50
4	BRS	L5	2	(substrate and ceramic adj fiber and (dry\$3 dri\$3) and binder and impregnat\$4 and calcin\$4 and fir\$3).clm.	US-PGPUB	2006/05/2 2 11:52
5	BRS	L6	0	("2004/0231307").URPN.	USPAT	2006/05/2 2 11:53

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	Hits	Search Text	DBs	Time Stamp
6	126	(substrate) and ceramic adj fiber and (dry\$3 dri\$3) and binder and impregnat\$4 and calcin\$4 and fir\$3	US-PGPUB ; USPAT ; USOCR ; EPO; JPO; DERWE NT	2006/05/2 2 11:58
7	4	((("6913059") or ("6287510") or ("20030165638") or ("20040231307"))).PN.	US-PGPUB ; USPAT	2006/05/2 2 12:05
8	0	("2004/0231307").URPN.	USPAT	2006/05/2 2 12:05
9	3	("2003/0165638").URPN.	USPAT	2006/05/2 2 12:05
10	0	("6913059").URPN.	USPAT	2006/05/2 2 12:06
11	2	("20030165638" "6582490").PN.	US-PGPUB ; USPAT ; USOCR	2006/05/2 2 12:06
12	0	("6287510").URPN.	USPAT	2006/05/2 2 12:06
13	6	("3885977" "4080414" "4758272" "4992233" "5427601" "6200526").PN.	US-PGPUB ; USPAT ; USOCR	2006/05/2 2 12:06